



BSI Standards Publication

Process management for avionics — Counterfeit prevention

Part 1: Avoiding the use of counterfeit,
fraudulent and recycled electronic
components

National foreword

This Published Document is the UK implementation of IEC/TS 62668-1:2016. It supersedes PD IEC/TS 62668-1:2014 which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee GEL/107, Process management for avionics.

A list of organizations represented on this committee can be obtained on request to its secretary.

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**Process management for avionics – Counterfeit prevention –
Part 1: Avoiding the use of counterfeit, fraudulent and recycled electronic
components**

INTERNATIONAL
ELECTROTECHNICAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**PROCESS MANAGEMENT FOR AVIONICS –
COUNTERFEIT PREVENTION –**
**Part 1: Avoiding the use of counterfeit, fraudulent
and recycled electronic components**

FOREWORD

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- the subject is still under technical development or where, for any other reason, there is the future but no immediate possibility of an agreement on an International Standard.

Technical specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC TS 62668-1, which is a technical specification, has been prepared by IEC technical committee 107: Process management for avionics.

This third edition cancels and replaces the second edition, published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) identified that the Chinese RECS scheme is no longer maintained (in 4.2 and where appropriate as agreed with CEPREI);
- b) added a reference to AS/EN/JISQ 9100 which at the next revision (revision D) will contain an anti-counterfeit requirement which may be used to satisfy the requirements of 4.2;
- c) added reference to the now published SAE AS6496 for franchised distributors, to USA DFARS rule 252.246.7007 and to UK Defence Standard 05-135;
- d) added reference to more GAO, OECD and ICC reports in 4.5.1;
- e) updated weblinks and other references.

The text of this technical specification is based on the following documents:

Enquiry draft	Report on voting
107/267/DTS	107/277/RVC

Full information on the voting for the approval of this technical specification can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the IEC/EC Directives, Part 2.

A list of all the parts in the IEC 62668 series, published under the general title *Process management for avionics – Counterfeit prevention*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- transformed into an International standard,
- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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PROCESS MANAGEMENT FOR AVIONICS – COUNTERFEIT PREVENTION –

Part 1: Avoiding the use of counterfeit, fraudulent and recycled electronic components

1 Scope

This part of IEC 62668, which is a Technical Specification, defines requirements for avoiding the use of counterfeit, recycled and fraudulent components used in the aerospace, defence and high performance (ADHP) industries. It also defines requirements for ADHP industries to maintain their intellectual property (IP) for all of their products and services. The risks associated with purchasing components outside of franchised distributor networks are considered in IEC TS 62668-2. Although developed for the avionics industry, this specification may be applied by other high performance and high reliability industries at their discretion.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TS 62239-1, *Process management for avionics – Management plan – Part 1: Preparation and maintenance of an electronic components management plan*

IEC TS 62668-2, *Process management for avionics – Counterfeit prevention – Part 2: Managing electronic components from non-franchised sources*

ISO 9001, *Quality management systems – Requirements*

AS/EN/JISQ 9100, *Quality Management Systems – Requirements for Aviation, Space and Defense Organizations*

AS/EN/JISQ 9110:2013, *Quality Maintenance Systems – Aerospace – Requirements for Maintenance Organizations*

3 Terms, definitions and abbreviations

3.1 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

3.1.1

aftermarket source

reseller which may or may not be under contract with the original component manufacturer (OCM), or is sometimes a component “re-manufacturer”, under contract with the OCM

Note 1 to entry: The reseller accumulates inventories of encapsulated or non-encapsulated (wafer) components whose end of life date has been published by the OCM. These components are then resold at a profit to fill a need within the market for components that have become obsolete.